# **UNR92A5J**

# Silicon NPN epitaxial planar type

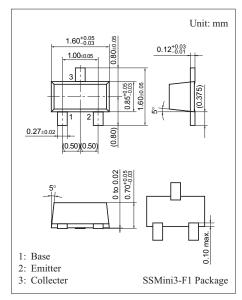
#### For digital circuits

#### ■ Features

- Optimum for high-density mounting and downsizing of the equipment
- Contribute to low power consumption

## ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                             | Symbol           | Rating      | Unit |  |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V <sub>CBO</sub> | 50          | V    |  |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | 50          | V    |  |
| Collector current                     | $I_{C}$          | 80          | mA   |  |
| Total power dissipation               | $P_{T}$          | 125         | mW   |  |
| Junction temperature                  | $T_j$            | 125         | °C   |  |
| Storage temperature                   | T <sub>stg</sub> | -55 to +125 | °C   |  |



### Marking Symbol: HC

#### Internal Connection

$$\begin{array}{c} R_1 \\ R_2 \\ \end{array} \qquad \begin{array}{c} C \\ \end{array}$$

## ■ Electrical Characteristics $T_a = 25$ °C±3°C

| Parameter                                    | Symbol               | Conditions   | Min  | Тур            | Max  | Unit |
|--|----------------------|--|------|----------------|------|------|
| Collector-base voltage (Emitter open)        | $V_{CBO}$            | $I_C = 10 \mu A, I_E = 0$  | 50   |                |      | V    |
| Collector-emitter voltage (Base open)        | V <sub>CEO</sub>     | $I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$                                | 50   |                |      | V    |
| Collector-base cutoff current (Emitter open) | I <sub>CBO</sub>     | $V_{CB} = 50 \text{ V}, I_{E} = 0$                                       |      |                | 0.1  | μΑ   |
| Collector-emitter cutoff current (Base open) | I <sub>CEO</sub>     | $V_{CE} = 50 \text{ V}, I_{B} = 0$                                       |      |                | 0.5  | μА   |
| Emitter-base cutoff current (Collector open) | I <sub>EBO</sub>     | $V_{EB} = 6 \text{ V}, I_C = 0$  |      |                | 0.01 | mA   |
| Forward current transfer ratio               | h <sub>FE</sub>      | $V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$                            | 160  |                | 460  | _    |
| Collector-emitter saturation voltage         | V <sub>CE(sat)</sub> | $I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA}$                              |      |                | 0.25 | V    |
| Output voltage high-level                    | $V_{OH}$             | $V_{CC} = 5 \text{ V}, V_{B} = 0.5 \text{ V}, R_{L} = 1 \text{ k}\Omega$ | 4.9  |                |      | V    |
| Output voltage low-level                     | V <sub>OL</sub>      | $V_{CC} = 5 \text{ V}, V_{B} = 2.5 \text{ V}, R_{L} = 1 \text{ k}\Omega$ |      |                | 0.2  | V    |
| Input resistance                             | $R_1$                |  | -30% | 10             | +30% | kΩ   |
| Resistance ratio                             | $R_1/R_2$            |  |      | $R_2 = \infty$ |      | _    |
| Transition frequency                         | $f_T$                | $V_{CB} = 10 \text{ V}, I_{E} = -2 \text{ mA}, f = 200 \text{ MHz}$      |      | 150            |      | MHz  |

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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